



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	TLE92466ED	<b>Issued</b>	08. April 2022
<b>MA#</b>	MA005557969		
<b>Package</b>	PG-DSO-36-72	<b>Weight*</b>	539.90 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.245	1.53	1.53	15271	15271
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		447	
	non noble metal	copper	7440-50-8	240.973	44.63	44.68	446327	446908
wire	non noble metal	copper	7440-50-8	3.263	0.60	0.60	6044	6044
encapsulation	organic material	carbon black	1333-86-4	0.824	0.15		1526	
	plastics	epoxy resin	-	32.133	5.95		59517	
	inorganic material	silicondioxide	60676-86-0	241.685	44.78	50.88	447646	508689
leadfinish	non noble metal	tin	7440-31-5	6.656	1.23	1.23	12328	12328
plating	noble metal	silver	7440-22-4	3.599	0.67	0.67	6666	6666
glue	plastics	epoxy resin	-	0.387	0.07		716	
	noble metal	silver	7440-22-4	1.824	0.34	0.41	3378	4094
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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